



Appendix 3 Product End-of-Life Disassembly instructions

Product Identification:

Marketing Name / Model	Description
HP Compaq t5720	t5720 (Windows XPe thin client)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment.

1.0 Items Requiring Selective Treatment

- 1.1 Items listed below are classified as requiring selective treatment.
- 1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Qty of items in product.
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 square cm	1
Batteries	All types including standard alkaline and lithium coin or button style batteries	1 Alkaline button style battery
Mercury containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 square cm	Includes background illuminated displays with gas discharge lamps	
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB / PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		1
External electrical cables and cords		
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		



2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Phillips Screwdriver	
Diagonal cutters (dikes)	

3.0 Product Disassembly Process

CMOS BATTERY	
1	Remove the two screws that secure the cover to the chassis (see Figure 1 below).
2	Pull the chassis cover off the chassis.
3	Disconnect the speaker cable from the system board.
4	After locating the battery on the system board, pull back on the clip that holds the battery in place, and then remove the battery (see Figure 2 below).
SYSTEM BOARD AND CAPACITOR	
1	Remove the four screws that secure the system board to the chassis (see Figure 3 below).
2	Loosen the four screws that secure each heatsink (eight total heatsink screws) (see Figure 3 below). You can either remove the heatsinks or leave them on the PCA.
3	Remove the two black screws, one on each side, near the back of the unit (see Figure 4 below). The screws hold the copper tubing in place. You can remove the copper tubing now or when you remove the system board from the unit.
4	Lift up the rear of the PC, and then lift the PCA up and out of the chassis.
5	Using diagonal cutters, cut the one capacitor as shown in Figure 5 below.

4.0 Illustrations

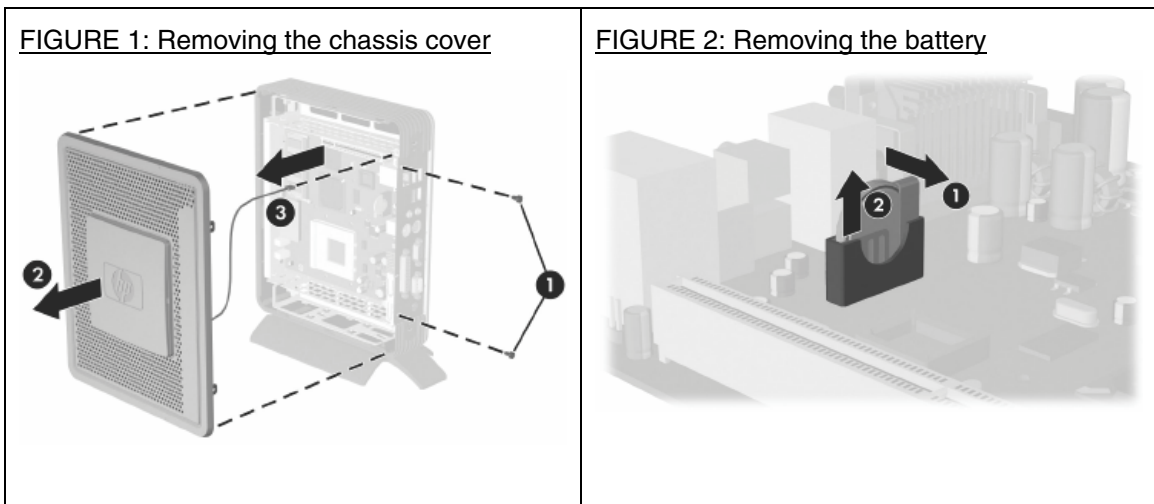


FIGURE 3: System board screw locations

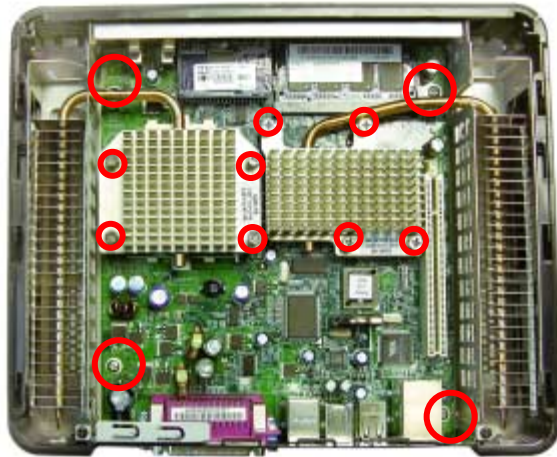


FIGURE 4: Copper tubing screw locations



FIGURE 5: Cut capacitor

